



Semiconductor Device Type: EN (UDX) 036 SQFN 6x6x1.0mm Matte Tin				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials			JEDEC 97 Product Marking and/or Pkg. Labeling e3	
Basic Substance	CAS Number	"Contained in" Sub-Component	% Total Weight	mg/part	ppm	65.88	(mg) Total	Mold Compound	% of Total Weight	79.85	
Silica, fused	60676-86-0	Mold Compound	71.865	59.289	718.650		Silica, fused	60676-86-0	90.00		
Epoxy Resin	Trade Secret	Mold Compound	3.873	3.195	38,727		Epoxy Resin	Trade Secret	4.85		
Phenolic Resin	Trade Secret	Mold Compound	3.873	3.195	38,727		Phenolic Resin	Trade Secret	4.85		
Carbon Black	1333-86-4	Mold Compound	0.240	0.198	2,396		Carbon Black	1333-86-4	0.30		
Copper	7440-50-8	Lead Frame	9.984	8.237	99,837		Total 100.00				
Iron	7439-89-6	Lead Frame	0.246	0.203	2,456	8.62	(mg) Total	Lead Frame	% of Total Weight	10.45	
Silver	7440-22-4	Lead Frame	0.199	0.164	1,991		Copper	7440-50-8	95.54		
Zinc	7440-66-6	Lead Frame	0.013	0.011	131		Iron	7439-89-6	2.35		
Phosphorous	7723-14-0	Lead Frame	0.009	0.007	86		Silver	7440-22-4	1.91		
Silver	7440-22-4	Die Attach	0.555	0.458	5,550		Zinc	7440-66-6	0.13		
Epoxy resin	68475-94-5	Die Attach	0.173	0.142	1,725		Phosphorous	7723-14-0	0.08		
Copper(II) oxide	1317-38-0	Die Attach	0.023	0.019	225		Total 100.00				
Silicon	7440-21-3	Chip (Die)	7.500	6.188	75,000	0.62	(mg) Total	Die Attach	% of Total Weight	0.75	
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.197	0.162	1,965		Silver	7440-22-4	74.00		
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.004	0.003	35		Epoxy resin	68475-94-5	23.00		
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	1.250	1.031	12,500		Copper(II) oxide	1317-38-0	3.00		
TOTALS:			100.000	82.500	1,000,000		Total 100.00				
0.0825 g Total Mass											
This semiconductor device and its homogenous materials comply with EU Directives: 2002/95/EC (27 January 2003) & Directive 2011/65/EU (08 June 2011) and 2015/863/EU (31 March 2015) and 2002/53/EC (End-of-Life Vehicles (ELV) without exemption (zero)											
Compliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data.											
If a chemical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology Incorporated's knowledge and belief as of the date of this document, there is no credible reason to believe that the unavoidable impurity concentration of the chemical substance, if any, is not below the threshold of regulatory concern for any regulatory scheme world-wide.											
Molding compounds used by Microchip meet the UL94 V0 flammability standard for plastics. You can access the UL iQTM family of databases to obtain a test report at http://ul.com/global/eng/pages/offering/industries/chemicals/plastics/											
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Assembled package referenced above is EU REACH compliant based on the latest SVHC candidate list of ECHA which can be found at http://echa.europa.eu/web/guest/candidate-list-table											
							6.19	Total (mg)	Chip (Die)	% of Total Weight	7.5
								Doped Silicon	7440-21-3	100.00	
							Total 100.00				
							0.17	(mg) Total	Wire Bond Copper palladium coated (CuPd)	% of Total Weight	0.2
								Copper	7440-50-8	98.25	
								Palladium	7440-05-3	1.75	
							Total 100.00				
							1.03	(mg) Total	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	% of Total Weight	1.25
								Tin	7440-31-5	100.00	
							Total 100.00				
							82.500				100.000